

APPLICATION DATA SHEET

Electronic Version v14

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Title of Invention	[MULTI-CHIP PACKAGE AND MANUFACTURING METHOD THEREOF]
Application Type :	regular, utility
Attorney Docket Number :	11239-US-PA
Correspondence address:	
Customer Number:	31561
	
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as our attorney(s) or agent(s) to prosecute the application identified above, and to transact all business in the United States Patent and Trademark Office connected therewith.